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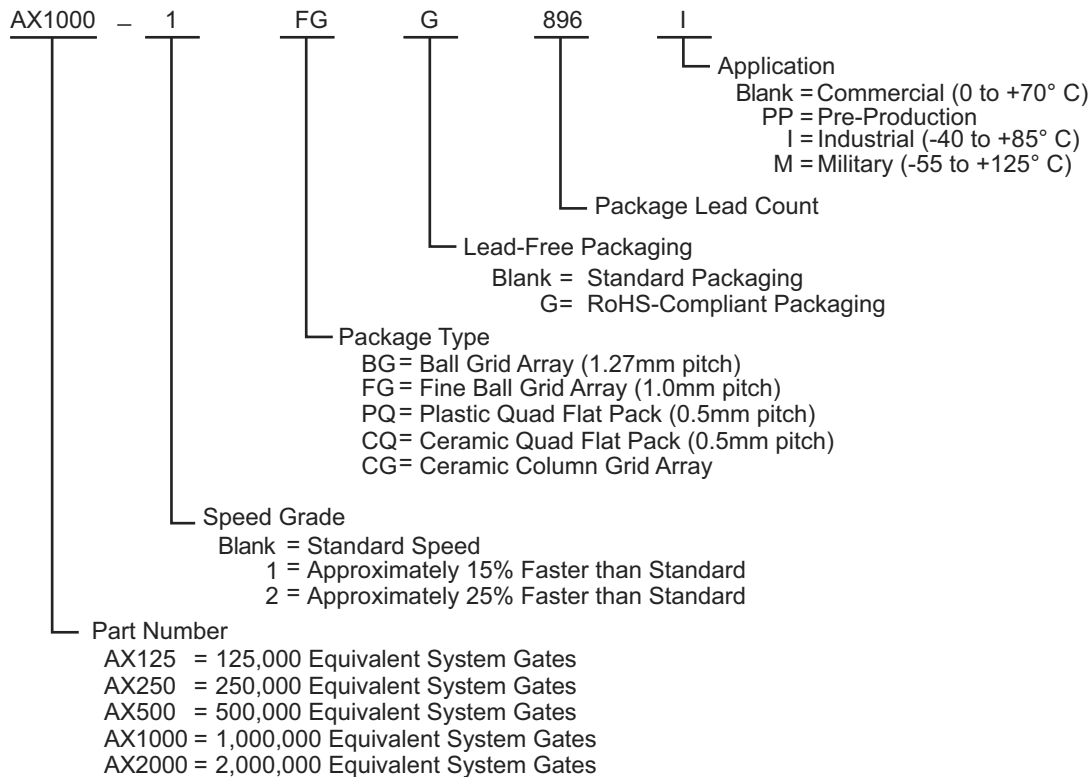
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Discontinued at Digi-Key
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	684
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	1152-BGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax2000-1fg1152i

Ordering Information



Device Resources

User I/Os (Including Clock Buffers)					
Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	115	115	–	–
CQ208	–	115	115	–	–
CQ256	–	–	–	–	136
FG256	138	138	–	–	–
FG324	168	–	–	–	–
CQ352	–	198	198	198	198
FG484	–	248	317	317	–
CG624	–	–	–	418	418
FG676	–	–	336	418	–
BG729	–	–	–	516	–
FG896	–	–	–	516	586
FG1152	–	–	–	–	684

Note: The FG256, FG324, and FG484 are footprint compatible with one another. The FG676, FG896, and FG1152 are also footprint compatible with one another.

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Table 2-5 • Different Components Contributing to the Total Power Consumption in Axcelerator Devices

Component	Definition	Device Specific Value (in $\mu\text{W}/\text{MHz}$)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

$$P_{total} = P_{dc} + P_{ac}$$

$$P_{dc} = ICCA * VCCA$$

$$P_{ac} = P_{HCLK} + P_{CLK} + P_{R-cells} + P_{C-cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$$

$$P_{HCLK} = (P1 + P2 * s + P3 * \sqrt{s}) * F_s$$

s = the number of R-cells clocked by this clock

F_s = the clock frequency

$$P_{CLK} = (P4 + P5 * s + P6 * \sqrt{s}) * F_s$$

s = the number of R-cells clocked by this clock

F_s = the clock frequency

$$P_{R-cells} = P7 * ms * F_s$$

ms = the number of R-cells switching at each F_s cycle

F_s = the clock frequency

$$P_{C-cells} = P8 * mc * F_s$$

mc = the number of C-cells switching at each F_s cycle

F_s = the clock frequency

$$P_{inputs} = P9 * pi * F_{pi}$$

pi = the number of inputs

F_{pi} = the average input frequency

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc} .

Table 2-6 • Package Thermal Characteristics

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP) ¹	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP) ¹	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA) ²	624	6.5	8.9	8.5	8	°C/W

Notes:

- θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.
- θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • Temperature and Voltage Timing Derating Factors
(Normalized to Worst-Case Commercial, $T_J = 70^\circ\text{C}$, $V_{CCA} = 1.425\text{V}$)

VCCA	Junction Temperature						
	-55°C	-40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

- The user can set the junction temperature in Designer software to be any integer value in the range of -55°C to 175°C.
- The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

I/O Clusters

Each I/O cluster incorporates two I/O modules, four RX modules, two TX modules, and a buffer module. In turn, each I/O module contains one Input Register (InReg), one Output Register (OutReg), and one Enable Register (EnReg) (Figure 2-5).

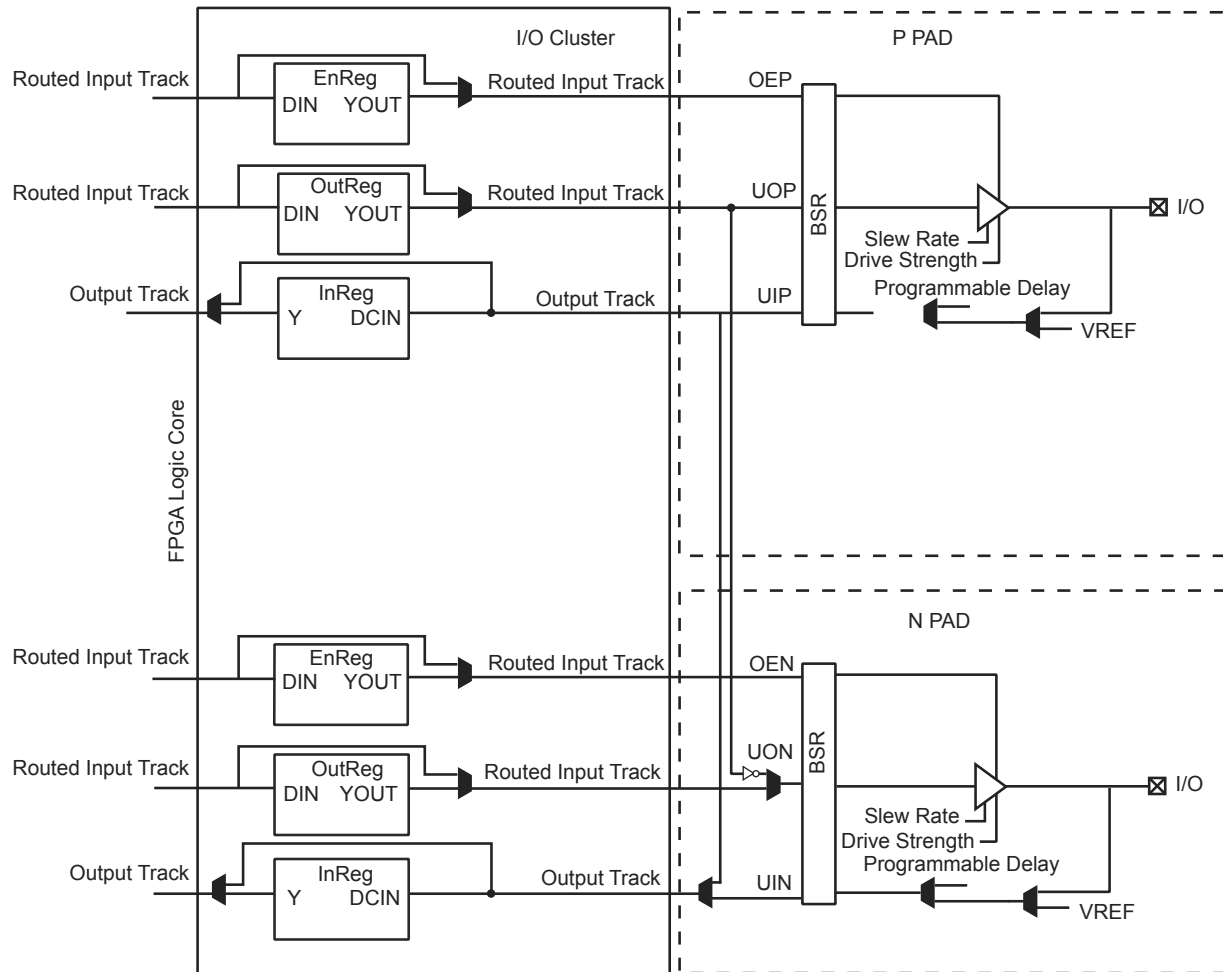


Figure 2-5 • I/O Cluster Interface

Using an I/O Register

To access the I/O registers, registers must be instantiated in the netlist and then connected to the I/Os. Usage of each I/O register (register combining) is individually controlled and can be selected/deselected using the PinEditor tool in the Designer software. I/O register combining can also be controlled at the device level, affecting all I/Os. Please note, the I/O register option is deselected by default in any given design.⁴

In addition, Designer software provides a global option to enable/disable the usage of registers in the I/Os. This option is design-specific. The setting for each individual I/O overrides this global option. Furthermore, the *global set fuse* option in the Designer software, when checked, causes all I/O registers to output logic High at device power-up.

4. Please note that register combining for multi fanout nets is not supported.

Table 2-15, Table 2-16, and Table 2-17 list all the available macro names differentiated by I/O standard, type, slew rate, and drive strength.

Table 2-15 • Macros for Single-Ended I/O Standards

Standard	VCCI	Macro Names
LVTTTL	3.3 V	CLKBUF, HCLKBUF INBUF, OUTBUF, OUTBUF_S_8, OUTBUF_S_12, OUTBUF_S_16, OUTBUF_S_24, OUTBUF_H_8, OUTBUF_H_12, OUTBUF_H_16, OUTBUF_H_24, TRIBUF, TRIBUF_S_8, TRIBUF_S_12, TRIBUF_S_16, TRIBUF_S_24, TRIBUF_H_8, TRIBUF_H_12, TRIBUF_H_16, TRIBUF_H_24, BIBUF, BIBUF_S_8, BIBUF_S_12, BIBUF_S_16, BIBUF_S_24, BIBUF_H_8, BIBUF_H_12, BIBUF_H_16, BIBUF_H_24
3.3 V PCI	3.3 V	CLKBUF_PCI, HCLKBUF_PCI, INBUF_PCI, OUTBUF_PCI, TRIBUF_PCI, BIBUF_PCI
3.3 V PCI-X	3.3 V	CLKBUF_PCI-X, HCLKBUF_PCI-X, INBUF_PCI-X, OUTBUF_PCI-X, TRIBUF_PCI-X, BIBUF_PCI-X
LVC MOS25	2.5 V	CLKBUF_LVC MOS25, HCLKBUF_LVC MOS25, INBUF_LVC MOS25, OUTBUF_LVC MOS25, TRIBUF_LVC MOS25, BIBUF_LVC MOS25
LVC MOS18	1.8 V	CLKBUF_LVC MOS18, HCLKBUF_LVC MOS18, INBUF_LVC MOS18, OUTBUF_LVC MOS18, TRIBUF_LVC MOS18, BIBUF_LVC MOS18
LVC MOS15 (JESD8-11)	1.5 V	CLKBUF_LVC MOS15, HCLKBUF_LVC MOS15, INBUF_LVC MOS15, OUTBUF_LVC MOS15, TRIBUF_LVC MOS15, BIBUF_LVC MOS15

Table 2-16 • I/O Macros for Differential I/O Standards

Standard	VCCI	Macro Names
LVPECL	3.3 V	CLKBUF_LVPECL, HCLKBUF_LVPECL, INBUF_LVPECL, OUTBUF_LVPECL
LVDS	2.5 V	CLKBUF_LVDS, HCLKBUF_LVDS, INBUF_LVDS, OUTBUF_LVDS

Table 2-17 • I/O Macros for Voltage-Referenced I/O Standards

Standard	VCCI	VREF	Macro Names
GTL+	3.3 V	1.0 V	CLKBUF_GTP33, HCLKBUF_GTP33, INBUF_GTP33, OUTBUF_GTP33, TRIBUF_GTP33, BIBUF_GTP33
GTL+	2.5 V	1.0 V	CLKBUF_GTP25, HCLKBUF_GTP25, INBUF_GTP25, OUTBUF_GTP25, TRIBUF_GTP25, BIBUF_GTP25
SSTL2 Class I	2.5 V	1.25 V	CLKBUF_SSTL2_I, HCLKBUF_SSTL2_I, INBUF_SSTL2_I, OUTBUF_SSTL2_I, TRIBUF_SSTL2_I, BIBUF_SSTL2_I
SSTL2 Class II	2.5 V	1.25 V	CLKBUF_SSTL2_II, HCLKBUF_SSTL2_II, INBUF_SSTL2_II, OUTBUF_SSTL2_II, TRIBUF_SSTL2_II, BIBUF_SSTL2_II
SSTL3 Class I	3.3 V	1.5 V	CLKBUF_SSTL3_I, HCLKBUF_SSTL3_I, INBUF_SSTL3_I, OUTBUF_SSTL3_I, TRIBUF_SSTL3_I, BIBUF_SSTL3_I
SSTL3 Class II	3.3 V	1.5 V	CLKBUF_SSTL3_II, HCLKBUF_SSTL3_II, INBUF_SSTL3_II, OUTBUF_SSTL3_II, TRIBUF_SSTL3_II, BIBUF_SSTL3_II
HSTL Class I	1.5 V	0.75 V	CLKBUF_HSTL_I, HCLKBUF_HSTL_I, INBUF_HSTL_I, OUTBUF_HSTL_I, TRIBUF_HSTL_I, BIBUF_HSTL_I

User I/O Naming Conventions

Due to the complex and flexible nature of the Axcelerator family's user I/Os, a naming scheme is used to show the details of the I/O. The naming scheme explains to which bank an I/O belongs, as well as the pairing and pin polarity for differential I/Os (Figure 2-7).

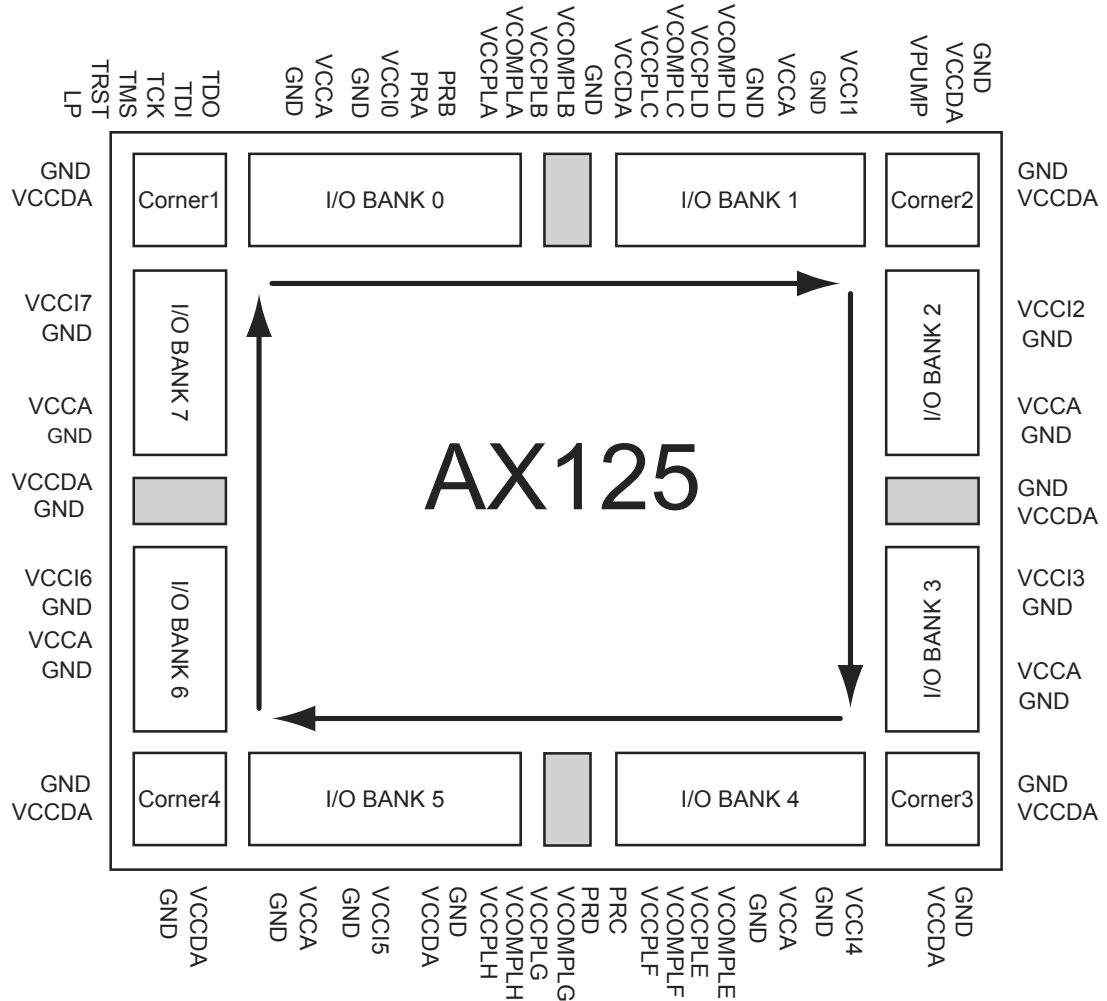
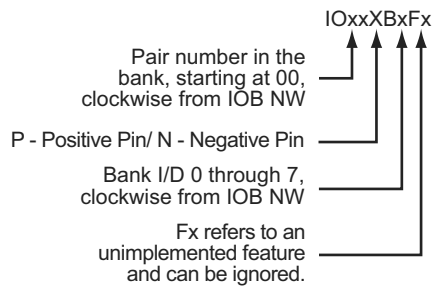


Figure 2-7 • I/O Bank and Dedicated Pin Layout



Examples:

IO12PB1F1 is the positive pin of the thirteenth pair of the first I/O bank (IOB NE). IO12PB1 combined with IO12NB1 form a differential pair.

For those I/Os that can be employed either as a user I/O or as a special function, the following nomenclature is used:

IOxxXBxFx/special_function_name

IOxxPB1Fx/xCLKx this pin can be configured as a clock input or as a user I/O.

Figure 2-8 • General Naming Schemes

I/O Standard Electrical Specifications

Table 2-18 • Input Capacitance

Symbol	Parameter	Conditions	Min.	Max.	Units
C_{IN}	Input Capacitance	$V_{IN} = 0, f = 1.0 \text{ MHz}$		10	pF
C_{INCLK}	Input Capacitance on HCLK and RCLK Pin	$V_{IN} = 0, f = 1.0 \text{ MHz}$		10	pF

Table 2-19 • I/O Input Rise Time and Fall Time*

Input Buffer	Input Rise/Fall Time (min.)	Input Rise/Fall Time (max.)
LVTTTL	No Requirement	50 ns
LVC MOS 2.5V	No Requirement	50 ns
LVC MOS 1.8V	No Requirement	50 ns
LVC MOS 1.5V	No Requirement	50 ns
PCI	No Requirement	50 ns
PCIX	No Requirement	50 ns
GTL+	No Requirement	50 ns
HSTL	No Requirement	50 ns
SSTL2	No Requirement	50 ns
HSTL3	No Requirement	50 ns
LVDS	No Requirement	50 ns
LVPECL	No Requirement	50 ns

*Note: *Input Rise/Fall time applies to all inputs, be it clock or data. Inputs have to ramp up/down linearly, in a monotonic way. Glitches or a plateau may cause double clocking. They must be avoided. For output rise/fall time, refer to the IBIS models for extraction.*

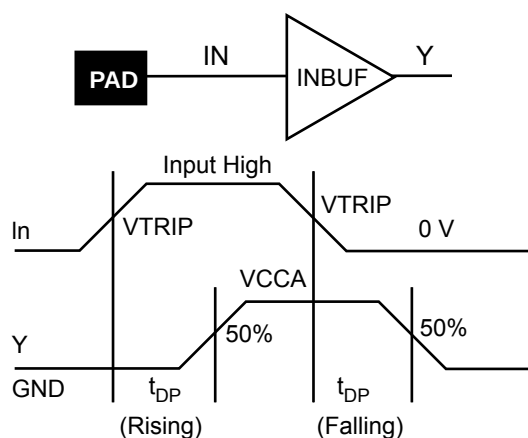


Figure 2-9 • Input Buffer Delays

Global Resources

One of the most important aspects of any FPGA architecture is its global resources or clocks. The Axcelerator family provides the user with flexible and easy-to-use global resources, without the limitations normally found in other FPGA architectures.

The AX architecture contains two types of global resources, the HCLK (hardwired clock) and CLK (routed clock). Every Axcelerator device is provided with four HCLKs and four CLKs for a total of eight clocks, regardless of device density.

Hardwired Clocks

The hardwired (HCLK) is a low-skew network that can directly drive the clock inputs of all sequential modules (R-cells, I/O registers, and embedded RAM/FIFOs) in the device with no antifuse in the path. All four HCLKs are available everywhere on the chip.

Timing Characteristics

Table 2-70 • AX125 Dedicated (Hardwired) Array Clock Networks
Worst-Case Commercial Conditions $V_{CCA} = 1.425\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
Dedicated (Hardwired) Array Clock Networks								
t _{HCKL}	Input Low to High		3.02		3.44		4.05	ns
t _{HCKH}	Input High to Low		3.03		3.46		4.06	ns
t _{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t _{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t _{HP}	Minimum Period	1.15		1.31		1.54		ns
t _{HMAX}	Maximum Frequency		870		763		649	MHz

Table 2-71 • AX250 Dedicated (Hardwired) Array Clock Networks
Worst-Case Commercial Conditions $V_{CCA} = 1.425\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
Dedicated (Hardwired) Array Clock Networks								
t _{HCKL}	Input Low to High		2.57		2.93		3.45	ns
t _{HCKH}	Input High to Low		2.61		2.97		3.50	ns
t _{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t _{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t _{HP}	Minimum Period	1.15		1.31		1.54		ns
t _{HMAX}	Maximum Frequency		870		763		649	MHz

PLL Configurations

The following rules apply to the different PLL inputs and outputs:

Reference Clock

The RefCLK can be driven by (Figure 2-50):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. CLK1 output of an adjacent PLL
3. [H]CLKxP (single-ended or voltage-referenced)
4. [H]CLKxP/[H]CLKxN pair (differential modes like LVPECL or LVDS)

Feedback Clock

The feedback clock can be driven by (Figure 2-51 on page 2-78):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. External [H]CLKxP/N I/O pad(s) from the adjacent PLL cell
3. An internal signal from the PLL block

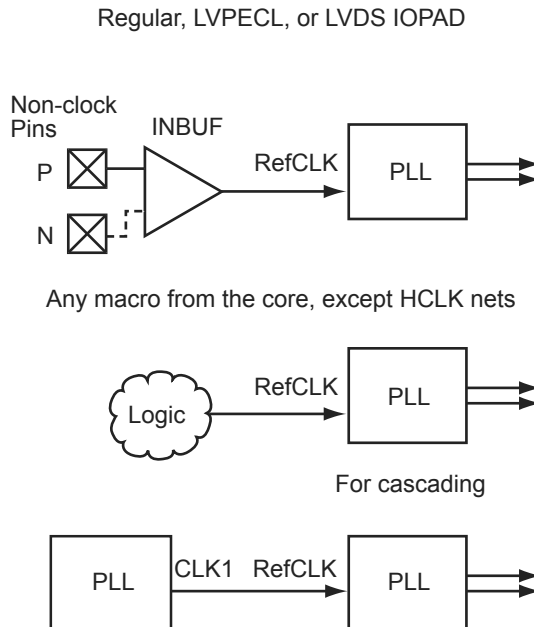


Figure 2-50 • Reference Clock Connections

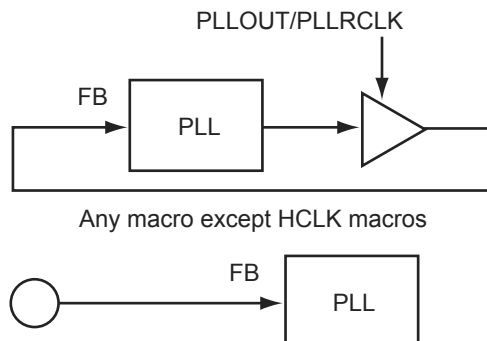


Figure 2-51 • Feedback Clock Connections

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10 μ s after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

Table 2-103 • JTAG Instruction Code

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 k Ω resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

BG729		BG729		BG729	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO218PB6F20	V2	IO236PB7F22	L1	IO255NB7F23	F5
IO219NB6F20	T1	IO237NB7F22	L4	IO255PB7F23	G5
IO219PB6F20	U1	IO237PB7F22	L3	IO256NB7F23	F3
IO220NB6F20	R5	IO238NB7F22	L6	IO256PB7F23	F4
IO220PB6F20	R6	IO238PB7F22	M6	IO257NB7F23	H7
IO221NB6F20	T3	IO239NB7F22	M8	IO257PB7F23	J7
IO221PB6F20	T4	IO239PB7F22	M7	Dedicated I/O	
IO222NB6F20	R2	IO240NB7F22	K2	GND	A1
IO222PB6F20	T2	IO240PB7F22	K1	GND	A2
IO223NB6F20	P8	IO241NB7F22	K4	GND	A25
IO223PB6F20	P9	IO241PB7F22	K3	GND	A26
IO224NB6F20	R3	IO242NB7F22	K5	GND	A27
IO224PB6F20	R4	IO242PB7F22	L5	GND	A3
Bank 7		IO243NB7F22	J2	GND	AC24
IO225NB7F21	P1	IO243PB7F22	J1	GND	AE1
IO225PB7F21	R1	IO244NB7F22	J4	GND	AE2
IO226NB7F21	P3	IO244PB7F22	J3	GND	AE25
IO226PB7F21	P2	IO245NB7F22	H2	GND	AE26
IO227NB7F21	N7	IO245PB7F22	H1	GND	AE27
IO227PB7F21	P7	IO246NB7F22	H4	GND	AE3
IO228NB7F21	P5	IO246PB7F22	H3	GND	AE5
IO228PB7F21	P4	IO247NB7F23	L8	GND	AF1
IO229NB7F21	N2	IO247PB7F23	L7	GND	AF2
IO229PB7F21	N1	IO248NB7F23	J6	GND	AF25
IO230NB7F21	N6	IO248PB7F23	K6	GND	AF26
IO230PB7F21	P6	IO249NB7F23	H5	GND	AF27
IO231NB7F21	N9	IO249PB7F23	J5	GND	AF3
IO231PB7F21	N8	IO250NB7F23	G2	GND	AG1
IO232NB7F21	N4	IO250PB7F23	G1	GND	AG2
IO232PB7F21	N3	IO251NB7F23	K8	GND	AG25
IO233NB7F21	M2	IO251PB7F23	K7	GND	AG26
IO233PB7F21	M1	IO252NB7F23	G4	GND	AG27
IO234NB7F21	M4	IO252PB7F23	G3	GND	AG3
IO234PB7F21	M3	IO253NB7F23	F2	GND	B1
IO235NB7F21	M5	IO253PB7F23	F1	GND	B2
IO235PB7F21	N5	IO254NB7F23	G6	GND	B25
IO236NB7F22	L2	IO254PB7F23	H6	GND	B26

FG676	
AX1000 Function	Pin Number
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

FG676	
AX1000 Function	Pin Number
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

FG676	
AX1000 Function	Pin Number
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG676	
AX1000 Function	Pin Number
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	Pin Number
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	Pin Number
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	B4
IO00PB0F0	A4
IO01NB0F0	F8
IO01PB0F0	F7
IO02NB0F0	D6
IO02PB0F0	E6
IO04NB0F0	A5
IO04PB0F0	B5
IO05NB0F0	H8
IO05PB0F0	G8
IO06NB0F0	D7
IO06PB0F0	E7
IO07NB0F0	D8
IO07PB0F0	E8
IO08NB0F0	C7
IO08PB0F0	C6
IO09NB0F0	G9
IO09PB0F0	H9
IO10NB0F0	A6
IO10PB0F0	B6
IO11NB0F0	H10
IO11PB0F0	G10
IO12NB0F1	E9
IO12PB0F1	F9
IO13NB0F1	E10
IO13PB0F1	F10
IO15NB0F1	F11
IO15PB0F1	G11
IO16NB0F1	A7
IO16PB0F1	B7
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	C9
IO18PB0F1	C8

FG896	
AX2000 Function	Pin Number
IO19NB0F1	D11
IO19PB0F1	E11
IO20PB0F1	B8
IO21NB0F1	H12
IO21PB0F1	H11
IO23NB0F2	A10
IO23PB0F2	A9
IO25NB0F2	F12
IO25PB0F2	G12
IO26NB0F2	B11
IO26PB0F2	B10
IO27NB0F2	D12
IO27PB0F2	E12
IO28NB0F2	C12
IO28PB0F2	C11
IO30NB0F2	A12
IO30PB0F2	A11
IO31NB0F2	F13
IO31PB0F2	G13
IO33NB0F2	H13
IO33PB0F2	J13
IO34NB0F3	B13
IO34PB0F3	B12
IO37NB0F3	E14
IO37PB0F3	E13
IO38NB0F3	B14
IO38PB0F3	A14
IO39NB0F3	H14
IO39PB0F3	J14
IO40NB0F3	B15
IO40PB0F3	A15
IO41NB0F3/HCLKAN	C14
IO41PB0F3/HCLKAP	D14
IO42NB0F3/HCLKBN	E15
IO42PB0F3/HCLKBP	D15

FG896	
AX2000 Function	Pin Number
Bank 1	
IO43NB1F4/HCLKCN	E17
IO43PB1F4/HCLKCP	E16
IO44NB1F4/HCLKDN	C17
IO44PB1F4/HCLKDP	D17
IO45NB1F4	A16
IO45PB1F4	B16
IO47NB1F4	H17
IO47PB1F4	J17
IO48NB1F4	A17
IO48PB1F4	B17
IO49NB1F4	H18
IO49PB1F4	J18
IO51NB1F4	F18
IO51PB1F4	G18
IO52NB1F4	B18
IO53NB1F4	D18
IO53PB1F4	C18
IO55NB1F5	H19
IO55PB1F5	G19
IO56NB1F5	B19
IO56PB1F5	A19
IO57NB1F5	E20
IO57PB1F5	E19
IO58NB1F5	C20
IO58PB1F5	C19
IO59NB1F5	B20
IO59PB1F5	A20
IO61NB1F5	F20
IO61PB1F5	F19
IO62NB1F5	A22
IO62PB1F5	A21
IO63NB1F5	D21
IO63PB1F5	D20
IO65NB1F6	G20

FG896	
AX2000 Function	Pin Number
IO303PB7F28	R1
IO304NB7F28	R7
IO304PB7F28	R6
IO306NB7F28	N2
IO306PB7F28	P2
IO307NB7F28	N3
IO307PB7F28	P3
IO308NB7F28	P9
IO308PB7F28	P8
IO309NB7F28	P4
IO309PB7F28	P5
IO310NB7F29	P7
IO310PB7F29	P6
IO311NB7F29	L1
IO311PB7F29	M1
IO312NB7F29	M5
IO312PB7F29	N5
IO313NB7F29	M4
IO313PB7F29	N4
IO315NB7F29	L2
IO315PB7F29	M2
IO316NB7F29	N7
IO316PB7F29	N6
IO317NB7F29	L3
IO317PB7F29	M3
IO318NB7F29	N8
IO318PB7F29	N9
IO320NB7F29	L6
IO320PB7F29	M6
IO321NB7F30	K4
IO321PB7F30	L4
IO322NB7F30	M8
IO322PB7F30	M7
IO323NB7F30	J1
IO323PB7F30	K1

FG896	
AX2000 Function	Pin Number
IO324NB7F30	K5
IO324PB7F30	L5
IO326NB7F30	G1*
IO326PB7F30	K2*
IO327NB7F30	J4
IO327PB7F30	J3
IO328NB7F30	L8
IO328PB7F30	L7
IO329NB7F30	G2
IO329PB7F30	H2
IO330NB7F30	G3
IO330PB7F30	H3
IO331NB7F30	K8
IO331PB7F30	K7
IO332NB7F31	J6
IO332PB7F31	K6
IO333NB7F31	D1
IO333PB7F31	D2
IO334NB7F31	G4
IO334PB7F31	H4
IO335NB7F31	F2
IO335PB7F31	F1
IO336NB7F31	H5
IO336PB7F31	J5
IO337NB7F31	E2
IO337PB7F31	E1
IO338NB7F31	H7
IO338PB7F31	J7
IO339NB7F31	F4
IO339PB7F31	F3
IO340NB7F31	F5
IO340PB7F31	G5
IO341NB7F31	G6
IO341PB7F31	H6
Dedicated I/O	

FG896	
AX2000 Function	Pin Number
GND	A13
GND	A18
GND	A2
GND	A23
GND	A29
GND	A8
GND	AA10
GND	AA21
GND	AA28
GND	AA3
GND	AB2
GND	AB22
GND	AB29
GND	AB9
GND	AC1
GND	AC30
GND	AE25
GND	AE6
GND	AF26
GND	AF5
GND	AG27
GND	AG4
GND	AH10
GND	AH15
GND	AH16
GND	AH21
GND	AH28
GND	AH3
GND	AJ1
GND	AJ2
GND	AJ22
GND	AJ29
GND	AJ30
GND	AJ9
GND	AK13

CG624	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	D7*
IO00PB0F0	E7*
IO01NB0F0	G7
IO01PB0F0	G6
IO02NB0F0	B5
IO02PB0F0	B4
IO04PB0F0	C7
IO05NB0F0	F8
IO05PB0F0	F7
IO06NB0F0	H8
IO06PB0F0	H7
IO11NB0F0	J8
IO11PB0F0	J7
IO12PB0F1	B6
IO13NB0F1	E9*
IO13PB0F1	D8*
IO15NB0F1	C9
IO15PB0F1	C8
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	G9
IO19PB0F1	G8
IO20PB0F1	B7
IO23NB0F2	F10
IO23PB0F2	F9
IO26NB0F2	C11*
IO26PB0F2	B8*

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO27NB0F2	H10
IO27PB0F2	H9
IO28NB0F2	A9
IO28PB0F2	B9
IO30NB0F2	B11
IO30PB0F2	B10
IO31NB0F2	E11
IO31PB0F2	F11
IO33NB0F2	D12
IO33PB0F2	D11
IO34NB0F3	A11
IO34PB0F3	A10
IO37NB0F3	J13
IO37PB0F3	K13
IO38NB0F3	H11
IO38PB0F3	G11
IO40PB0F3	B12
IO41NB0F3/HCLKAN	G13
IO41PB0F3/HCLKAP	G12
IO42NB0F3/HCLKBN	C13
IO42PB0F3/HCLKBP	C12
Bank 1	
IO43NB1F4/HCLKCN	G15
IO43PB1F4/HCLKCP	G14
IO44NB1F4/HCLKDN	B14
IO44PB1F4/HCLKDP	B13
IO45NB1F4	H13
IO47NB1F4	D14
IO47PB1F4	C14
IO48NB1F4	A16
IO48PB1F4	A15
IO49PB1F4	H15

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO51NB1F4	E15
IO51PB1F4	F15
IO52NB1F4	A17
IO55NB1F5	G16
IO55PB1F5	H16
IO56NB1F5	A20
IO56PB1F5	A19
IO57NB1F5	D16
IO57PB1F5	D15
IO58NB1F5	A22
IO58PB1F5	A21
IO59NB1F5	F16
IO61NB1F5	G17
IO61PB1F5	H17
IO62NB1F5	B17
IO62PB1F5	B16
IO63NB1F5	H18
IO65NB1F6	C17
IO66PB1F6	B18
IO67NB1F6	J18
IO67PB1F6	J19
IO68NB1F6	B20
IO68PB1F6	B19
IO69NB1F6	E17
IO69PB1F6	F17
IO70NB1F6	B22
IO70PB1F6	B21
IO71PB1F6	G18
IO73NB1F6	G19
IO74NB1F6	C19
IO74PB1F6	C18
IO75NB1F6	D18

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO157PB3F14	U20
IO158NB3F14	AB25
IO158PB3F14	AA25
IO160PB3F14	W24
IO161NB3F15	U24
IO161PB3F15	U23
IO162NB3F15	AA24
IO162PB3F15	Y24
IO163NB3F15	V22
IO163PB3F15	U22
IO164NB3F15	V23
IO164PB3F15	V24
IO166NB3F15	AB24
IO167NB3F15	V21
IO167PB3F15	U21
IO168NB3F15	Y23
IO168PB3F15	AA23
IO169NB3F15	W22*
IO169PB3F15	W23*
IO170NB3F15	Y22
IO170PB3F15	Y21
Bank 4	
IO171NB4F16	AC20*
IO171PB4F16	AC21*
IO172NB4F16	W20
IO172PB4F16	Y20
IO173NB4F16	AD21
IO173PB4F16	AD22
IO174NB4F16	AA19
IO176NB4F16	Y18
IO176PB4F16	Y19
IO177NB4F16	AB19

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO177PB4F16	AB18
IO182NB4F17	V19
IO182PB4F17	W19
IO183PB4F17	AC19
IO184NB4F17	AB17
IO184PB4F17	AC17
IO185NB4F17	AD19
IO185PB4F17	AD20
IO187PB4F17	AC18
IO188NB4F17	Y17
IO188PB4F17	AA17
IO189PB4F17	AE22
IO191NB4F17	W18
IO191PB4F17	V18
IO192PB4F17	U18
IO195PB4F18	AE21
IO196NB4F18	AB16
IO197NB4F18	AD17
IO197PB4F18	AD18
IO198NB4F18	V17
IO198PB4F18	W17
IO199NB4F18	AE19
IO199PB4F18	AE20
IO200NB4F18	AC15
IO201NB4F18	AD15
IO201PB4F18	AD16
IO202NB4F18	Y15
IO202PB4F18	Y16
IO206NB4F19	AB14
IO206PB4F19	AB15
IO207NB4F19	AE15
IO207PB4F19	AE16

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO208PB4F19	W16
IO209NB4F19	AE14
IO210NB4F19	V15
IO210PB4F19	V16
IO211NB4F19	AD14
IO211PB4F19	AC14
IO212NB4F19/CLKEN	W14
IO212PB4F19/CLKEP	W15
IO213NB4F19/CLKFN	AC13
IO213PB4F19/CLKFP	AD13
Bank 5	
IO214NB5F20/CLKGN	W13
IO214PB5F20/CLKGP	Y13
IO215NB5F20/CLKHN	AC12
IO215PB5F20/CLKHP	AD12
IO216NB5F20	U13
IO216PB5F20	V13
IO217NB5F20	AE10
IO217PB5F20	AE11
IO218NB5F20	W11
IO218PB5F20	W12
IO222NB5F20	AA11
IO222PB5F20	Y11
IO223PB5F21	AE9
IO225NB5F21	AE6
IO225PB5F21	AE7
IO226NB5F21	Y10
IO226PB5F21	W10
IO227PB5F21	T13
IO228NB5F21	AB10
IO228PB5F21	AB11
IO229NB5F21	AD9

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.